



Product Change Notification

113012 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: 113012 - 00
Change Title: Intel® Spare Power Distribution Board
FUPPDBHC
PCN 113012-00, Product Design
Change Capacitor and Cable
Date of Publication: May 07, 2014

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

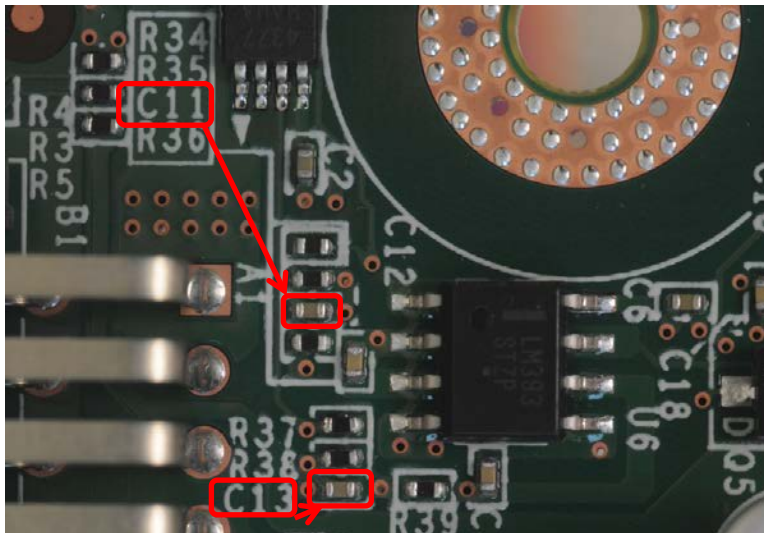
Date Customer Must be Ready to Receive Post-Conversion Material *:	May 22, 2014
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** Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.*

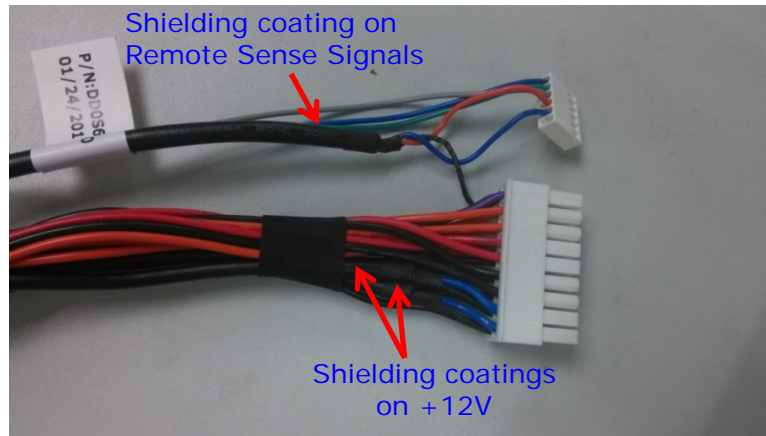
Description of Change to the Customer:

Intel is implementing the following changes on the Intel® Spare Power Distribution Board FUPPDBHC:

1. Increase the capacitor values of C11 and C13 from 0.1 μ F to 2.2 μ F to extend the duration of the Over Current Protection circuit from 0.6ms to 8.0ms. Please refer to the TA-1056-01 for more details.



2. Add shielding coatings on the power rail +12V and the remote sense signals respectively to prevent the noise coupling from the +12V signal wires to the remote sense signal wires. Please refer to the TA-1047-01 for more details.



Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from this change, but encourages customers to understand the change and determine the impact on their applications.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Pre Change PBA	Post Change TA	Post Change PBA
FUPPDBHC	916813	G29609-001	G15585-401	G29609-002	G15585-402

PCN Revision History:

Date of Revision:

May 7, 2014

Revision Number:

00

Reason:

Originally Published PCN